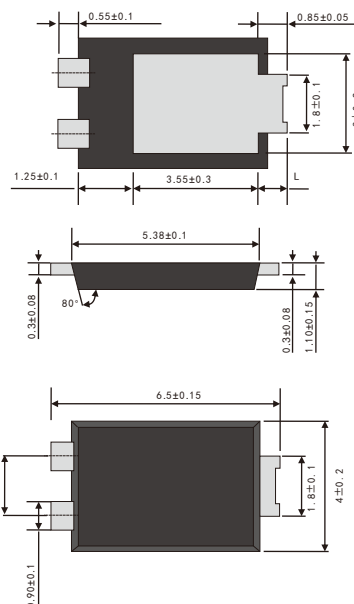


FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
 - Metal silicon junction ,majority carrier conduction
 - Guard ring for overvoltage protection
 - Low power loss ,high efficiency
 - High current capability ,low forward voltage drop
 - High surge capability
 - Very low profile-typical height of 1.1mm
 - Ideal for automated placement
 - High temperature soldering guaranteed:260°C/10 seconds at terminals
- Component in accordance to RoHS 2011/65/EU



TO-277

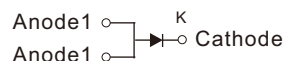


MECHANICAL DATA

- Case: TO-277 molded plastic body
- Terminals: Plated axial leads, solderable per MIL-STD-750,method 2026
- Mounting Position: Any
- Weight: 0.092 grams (approx)

TYPICAL APPLICATIONS

For use in low voltage ,high frequency inverters ,DC/DC converters, free wheeling ,and polarity protection applications



Dimensions in inches and (millimeters)

MAXIMUM RATINGS

(Ratings at 25°C ambient temperature unless otherwise specified)

Parameter	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	100	V
Maximum average forward rectified current	I _{F(AV)}	30.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method at rated TL)	I _{FSM}	200	A
Operating junction temperature range	T _J	-55 to +150	°C
Storage temperature range	T _{stg}	-55 to +150	°C

RATINGS AND CHARACTERISTIC OF SP30U100L

ELECTRICAL CHARACTERISTICS (T_A=25°C Unless otherwise noted)

Parameter	Test Conditions		Symbol	TYP.	MAX.	Unit
Instantaneous forward voltage	T _J =25°C	I _F =30A	V _F ¹⁾	0.75	0.77	V
		I _F =10A		0.54	–	
		I _F =5A		0.47	–	
	T _J =125°C	I _F =30A		0.73	–	
		I _F =10A		0.51	–	
		I _F =5A		0.40	–	
Reverse current	V _R =100V	T _A =25°C	I _R ²⁾	30	100	μA
		T _A =100°C		5	–	mA
		T _A =125°C		20	–	
Typical junction capacitance	4V, 1MHz		C _J	1200		pF

Notes: 1.Pulse test: 300 μs pulse width, 1% duty cycle

2.Pulse test: pulse width ≤ 40ms

THERMAL CHARACTERISTICS

Parameter	Symbol	TO-277	Unit
Typical thermal resistance ³⁾	R _{θJA} ⁴⁾	60.0	°C/W
	R _{θJL}	3.0	

3 Units mounted on recommended PCB 1 oz. Pad layout

4 The heat generated must be less than thermal conductivity from junction to ambient: dP_D/dt_J < 1/R_{θJA}

AVAILABLE PACK INFORMATION

Product code	Pack	Reel Size (mm)	Quantity (pcs/reel)	Box Size L×W×H (mm)	Quantity (reel/box)	Carton Size L×W×H (mm)	Quantity (box/carton)
SP30U100L-TO-277	T/R	φ 330	5000	338×338×40	2	365×365×360	7

RATINGS AND CHARACTERISTIC OF SP30U100L

FIG.1-FORWARD CURRENT DERATING CURVE

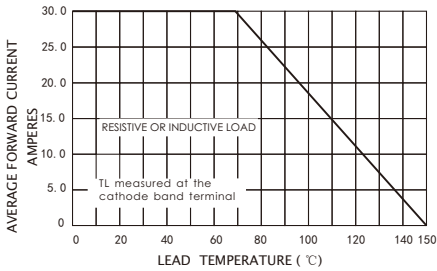


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

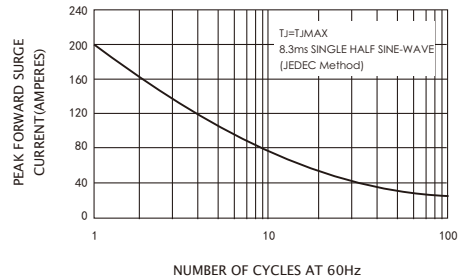


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

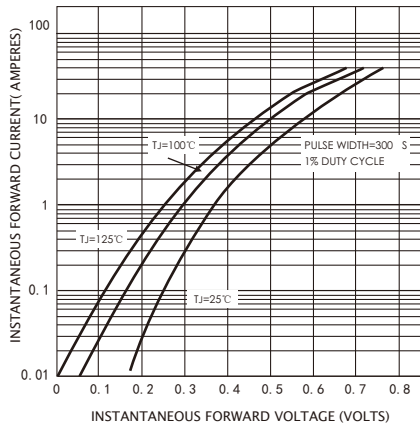


FIG.4-TYPICAL REVERSE CHARACTERISTICS

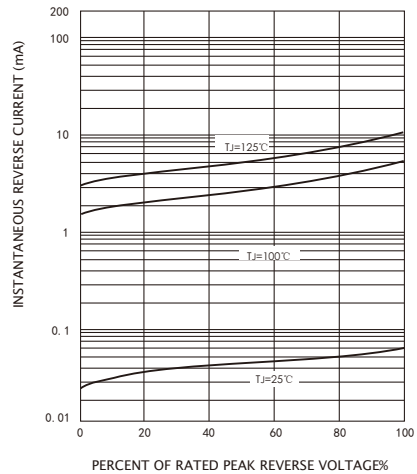


FIG.5-TYPICAL JUNCTION CAPACITANCE

